

## **AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph beginning on page 7, line 4, as follows to correct a typographical error.

MEMS die 102 includes a seal ring 122A and the cap section 104 includes a seal ring 122B. When the MEMS die 102 and the cap section 104 are coupled together, the seal rings 122A and 122B are pressed together to form a hermetical seal. The seal rings 122A and 122B can be sealed using solder, gold thermocompression bonding (TCB), gold thermosonic bonding (TSB), or the like. Thus, when the MEMS RF switch module 100 is sealed, the cavity around RF switch array 124 is sterile to reduce the affects of dust and other ~~containments~~ contaminants on the performance of the RF switch array 124. In one embodiment, the seal rings 122A and 122B are metal. In another embodiment, only one of MEMS die 102 or cap section 104 includes the seal ring prior to coupling MEMS die 102 and cap section 104 together.